

## EAST Search History

| Ref # | Hits   | Search Query   | DBs  | Default Operator | Plurals | Time Stamp          |
|-------|--------|--|--|------------------|---------|---------------------|
| L1    | 2      | US-20070254986-\$ did.   | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2009/06/18<br>12:26 |
| L3    | 381259 | curative hardener (cross adj2 linker) crosslinker ((curing hardening (cross adj2 linking) crosslinking) adj2 (agent promoter)) | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2009/06/18<br>12:55 |
| L4    | 742437 | epox\$6 diepox\$6 triepox\$6 polyepox\$6 glycidyl\$ diglycidyl\$ triglycidyl\$ tetraglycidyl\$ polyglycidyl\$                  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2009/06/18<br>12:55 |
| L5    | 280    | L3.ab. and L4.ab. and pitch.ab.  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2009/06/18<br>12:55 |
| L6    | 7      | L3.ab. and L4.ab. and (mesophase near5 pitch).ab.  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2009/06/18<br>12:55 |
| L7    | 8      | L3.ab. and L4.ab. and pitch.ab. and (mesophase near5 pitch)  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2009/06/18<br>12:57 |
| L8    | 9      | L3.ab. and L4.ab. and pitch and (mesophase near5 pitch)  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2009/06/18<br>12:58 |
| L9    | 96     | (L3 same L4) and pitch and (mesophase near5 pitch)   | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2009/06/18<br>12:58 |
| L10   | 29     | (L3 same L4) and pitch and (mesophase near5 pitch) and (semiconductor (semi adj2 conductor))                                   | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2009/06/18<br>12:59 |

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| L11 | 39   | (L3 and L4) and pitch and (mesophase near5 pitch) and (semiconductor (semi adj2 conductor))   | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2009/06/18<br>13:04 |
| L12 | 41   | (L3 and L4) and pitch and (mesophase near5 pitch) and (semiconductor (semi adj2 conductor) ((sealing encapsulat \$5) near5 electronic))             | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2009/06/18<br>13:08 |
| L13 | 2    | 112 not 111   | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2009/06/18<br>13:09 |
| L14 | 2683 | (L3 and L4) and pitch and (semiconductor (semi adj2 conductor) ((sealing encapsulat \$5) near5 electronic))   | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2009/06/18<br>13:10 |
| L15 | 1767 | ((L3 same L4) (l3.ab. and l4.ab.)) and pitch and (semiconductor (semi adj2 conductor) ((sealing encapsulat \$5) near5 electronic))                  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2009/06/18<br>13:11 |
| L16 | 32   | ((L3 same L4) (l3.ab. and l4.ab.)) and (pitch same mesophase) and (semiconductor (semi adj2 conductor) ((sealing encapsulat \$5) near5 electronic)) | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2009/06/18<br>13:11 |
| L17 | 122  | ((L3 same L4) (l3.ab. and l4.ab.)) and (pitch with carbon) and (semiconductor (semi adj2 conductor) ((sealing encapsulat \$5) near5 electronic))    | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2009/06/18<br>13:13 |
| L18 | 1    | "mcmb green"  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2009/06/18<br>13:32 |
| L19 | 2    | jp-2001114986-\$.did.   | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2009/06/18<br>13:34 |
| L20 | 1    | 2001-484833.NRAN.   | DERWENT  | OR | OFF | 2009/06/18<br>13:34 |

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| L21 | 26      | ("6528559").pn. kr-20010074819-\$.did. jp-60119760-\$.did. jp-63179921-\$.did. jp-11060904-\$.did. jp-2003160713-\$.did. jp-2004256687-\$.did. jp-09077846-\$.did. jp-06184131-\$.did. jp-05287052-\$.did. jp-2003327792-\$.did. jp-62227955-\$.did. jp-10259292-\$.did. jp-2001335620-\$.did. | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>13:50 |
| L22 | 3       | l21 and pitch  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>14:07 |
| L23 | 6       | jp-2004256687-\$.did. jp-09077846-\$.did. jp-06184131-\$.did.  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>14:09 |
| L24 | 3451    | L3 and pitch and (semiconductor (semi adj2 conductor) ((sealing encapsulat \$5) near5 electronic))   | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>14:12 |
| L25 | 3451    | L3 and (pitch mesopitch) and (semiconductor (semi adj2 conductor) ((sealing encapsulat \$5) near5 electronic))   | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>14:12 |
| L26 | 1615273 | (L3 thermoset thermosetting).ab. (pitch mesopitch).ab. (semiconductor (semi adj2 conductor) ((sealing encapsulat \$5) near5 electronic)).ab.   | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>14:13 |
| L27 | 1003    | l25 and l26  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>14:13 |
| L28 | 1531907 | (L3).ab. (pitch mesopitch).ab. (semiconductor (semi adj2 conductor) ((sealing encapsulat \$5) near5 electronic)).ab.   | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>14:13 |
| L29 | 956     | l25 and l28  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>14:13 |

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| L30 | 8   | l29 and (mesophase (meso adj2 phase))  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>14:14 |
| L31 | 3   | l29 and (pitch with resistivity)   | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>14:16 |
| L32 | 97  | l29 and (resistivity)  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>14:17 |
| L33 | 323 | (mesophase (meso adj2 phase))<br>with pitch with (sphere<br>microsphere spherical<br>microspherical) | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>14:41 |
| L34 | 38  | l3 and l4 and l33  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>14:41 |
| L35 | 15  | l21 and l3 and l4  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>14:54 |
| L36 | 14  | l35 and (semiconductor (semi<br>adj2 conductor) ((sealing<br>encapsulat\$5) near5<br>electronic))    | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>14:55 |
| L37 | 23  | l21 and l4   | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>14:56 |
| L38 | 22  | l37 and (semiconductor (semi<br>adj2 conductor) ((sealing<br>encapsulat\$5) near5<br>electronic))    | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>14:56 |
| L39 | 283 | phosphazene near5 (crosslink<br>\$3 (cross adj2 link\$3))  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>15:18 |

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| L40 | 0      | l1.ab. and (phenol phenolic l3).<br>ab. and l39.ab.                         | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>15:19 |
| L41 | 24     | l4.ab. and (phenol phenolic l3).<br>ab. and l39.ab.                         | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>15:19 |
| L42 | 118    | tendou-k\$.in. tendou-k\$-\$.in.  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>15:30 |
| L43 | 485    | katayose-m\$.in. katayose-m\$-\$.<br>in.                                    | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>15:30 |
| L44 | 67     | l42 and l43   | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>15:30 |
| L45 | 927526 | l42 l43 hitachi.as.   | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>15:30 |
| L46 | 18     | l45 and l4.clm. and pitch.clm.  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>15:31 |
| L47 | 661    | 523/440.ccls. 523/468.ccls.   | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>15:33 |
| L48 | 5821   | 257/787.ccls. 257/788.ccls.<br>257/789.ccls. 257/793.ccls.<br>257/795.ccls. | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>15:34 |
| L49 | 103    | (l47 l48) and l4 and l3 and<br>pitch  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>15:34 |

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| L50 | 2       | (147 148) and 14 and 13 and pitch and (mesophase (meso adj2 phase))  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/18<br>15:34 |
| S25 | 496814  | silicone polysiloxane<br>polyorganosiloxane<br>polydiorganosiloxane<br>organopolysiloxane<br>organosiloxane<br>diorganopolysiloxane siloxane<br>organosilicone | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/02/14<br>09:00 |
| S26 | 317795  | curative hardener (cross adj2 linker) crosslinker ((curing hardening (cross adj2 linking) crosslinking) adj2 (agent promoter))                                 | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/06/28<br>14:33 |
| S27 | 1222941 | amine amino diamine diamino triamine triamino polyamine polyamino  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/12/12<br>13:13 |
| S28 | 605176  | epox\$6 diepox\$6 triepox\$6 polyepox\$6 glycidyl\$ diglycidyl\$ triglycidyl\$ tetraglycidyl\$ polyglycidyl\$  | US-PGPUB;<br>USPAT; USOCR;<br>FPRS; EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/02/14<br>09:01 |

6/18/09 3:42:06 PM

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